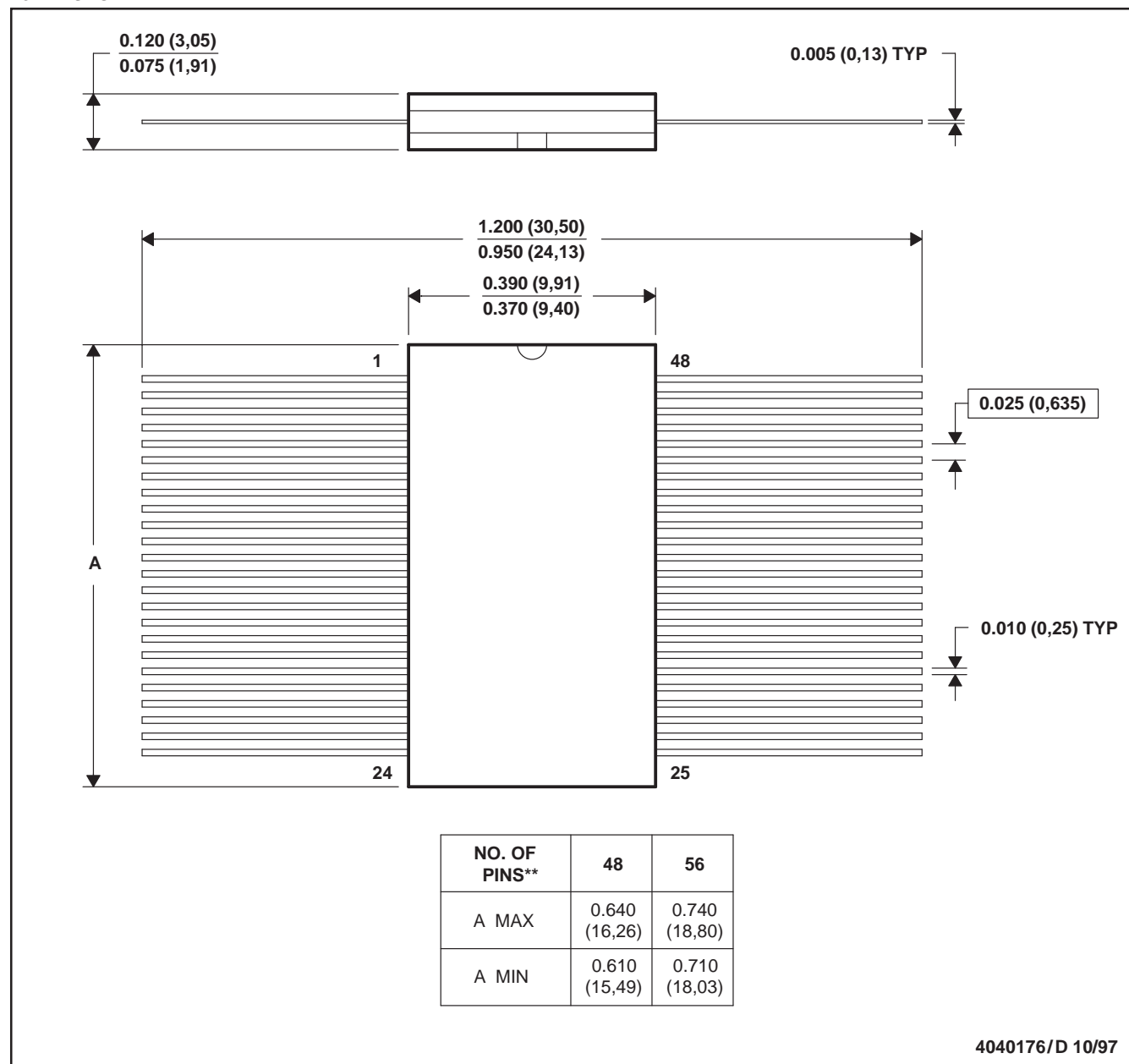


## WD (R-GDFP-F\*\*)

## CERAMIC DUAL FLATPACK

48-PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for pin identification only.  
 E. Falls within MIL-STD-1835: GDFP1-F48 and JEDEC MO-146AA  
 GDFP1-F56 and JEDEC MO-146AB

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